



Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT CHANGE NOTIFICATION

PCN: PCN165104

Date: December 23, 2016

Subject: Qualification of ZKT as an Alternate Assembly Site for Select Stacked Die 16-Lead SOIC Packages with Spacers and Copper Wire Bond.

To: GENERAL INBOX
PREMIER FARNELL
ProductChangeNotices@premierfarnell.com

Description of Change:

Cypress announces the qualification of Suzhou Zhen Kun Technology Limited (ZKT) as an alternate assembly site for select stacked die SOIC 16-Lead packages with spacers and copper bonding wires. ZKT is a world-class assembly facility, qualified to build standard grade products consistent with AEC-Q100. The qualification of this facility will enable Cypress to provide assembly operations to meet our customers' stringent quality and reliability requirements in our effort to continually provide world-class service.

SOIC 16-Lead stacked die packages assembled at ZKT Suzhou will use the following Bill of Materials (BoM).

		ZKT Bill of Materials	ASE-CL Bill of Materials
Die Attach Material	Bottom die	Yizbond 8511 (Epoxy)	EN-4900 (Epoxy)
	Spacer die	Lintec LE62 (Film)	ATB-125 (Film)
	Top die	Lintec LE62 (Film)	ATB-125 (Film)
Bonding Wire		0.8mil PdCu	0.8mil Cu
Mold Compound		Samsung SG8300HKT	Hitachi CEL9240
Lead Finish		Pure Tin	Pure Tin

There are no changes to ordering part numbers. Product datasheets remain the same and can be downloaded from Cypress website (www.cypress.com).

Benefit of Change:

Qualification of alternate manufacturing sites is part of the ongoing flexible manufacturing initiative announced by Cypress. The goal of the flexible manufacturing initiative is to provide the means for Cypress to continue to meet delivery commitments through dynamic, changing market conditions.

Affected Parts: 14

See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN may also be manufactured with new bill of materials.

Qualification Status:

As per specific list of major changes, this package has been qualified through series of tests planned on the Qualification Test Plan # 162905. The report for this QTP can be found as an attachment to this PCN.

Sample Status:

Qualification samples are not built ahead of time for all part numbers affected by this change. Please contact your local Cypress Sales representative for sample availability as soon as possible, but within 30 days of the date of this PCN, to place any sample orders

Approximate Implementation Date:

Effective 90 days from the date of this notification, all shipments of the affected part number listed above will be assembled at ZKT, Suzhou, China or other approved assembly sites.

Anticipated Impact:

Products manufactured with new bill of materials are completely compatible with existing product from a functional, parametric, and quality performance perspective.

Cypress recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration